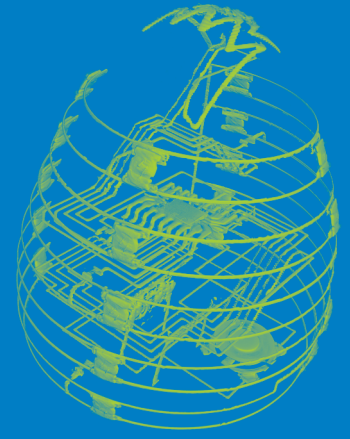


14<sup>th</sup> International Congress

# Molded Interconnect Devices



Patrick Bak, Xylon International GmbH

Amberg, Germany, 9<sup>th</sup> – 10<sup>th</sup> February 2021

## Call for Papers

### Steady Growth, new Developments and emerging Opportunities for MID Technologies

Mechatronic Integrated Devices (MID) are increasingly driven from many sides. With new series applications in consumer electronics, medical technology and the automotive industry, the success of MID technologies continues to grow. In addition, the Internet of Things, for which MID technologies offer unparalleled opportunities, is further shaping our environment. The publication of the VDI guideline 3719 and the resulting increase in quality and reliability of MID applications strengthens the market position from a completely different direction. Promising new process developments and the continued strong growth in printed electronics and additive manufacturing technologies, as well as the intersections of the two, will also enable further completely new applications. This will open up new applications and new markets.

The 14<sup>th</sup> International MID Congress of the Research Association 3-D MID e.V. presents, promotes and shares the developments in the fields of materials, manufacturing processes and technologies, but also launch strategies and business models as well as quality and reliability testing. It will be accompanied by an industrial exhibition, a presentation of current research results and a technical tour.

organized by  
Research Association  
Molded Interconnect Devices  
3-D MID e.V.

in cooperation with  
University of Erlangen-Nuremberg  
Institute for Factory Automation  
and Production Systems – FAPS



### Submission of Abstracts and Papers

Experts of industry and science are invited to present a paper on the topics shown in the figure on the next page. For this, abstracts in the extent of 500 words have to be provided via the online conference tool including the following details:

- Title of the paper
- Preferred classification  
(Industrial Track / Scientific Track)
- Allocation to field of topic
- Name and address of the author(s)

Further information and a template for your abstract is available at the congress pages on:

<https://www.3d-mid.de/en/congress-mid/>

Please note the dates stated below. Abstracts will be verified before acceptance by the program committee. All accepted contributions will be published in the congress proceedings. Information regarding the presentations will be sent separately. Speakers will be granted discounted participation fees.

### Important Dates

Submission of scientific papers	October 2 <sup>nd</sup> , 2020
Submission of presentations	January 11 <sup>th</sup> , 2021
Conference MID 2021	February 9 <sup>th</sup> – 10 <sup>th</sup> , 2021
Technical Tour	February 10 <sup>th</sup> , 2021

### Contact

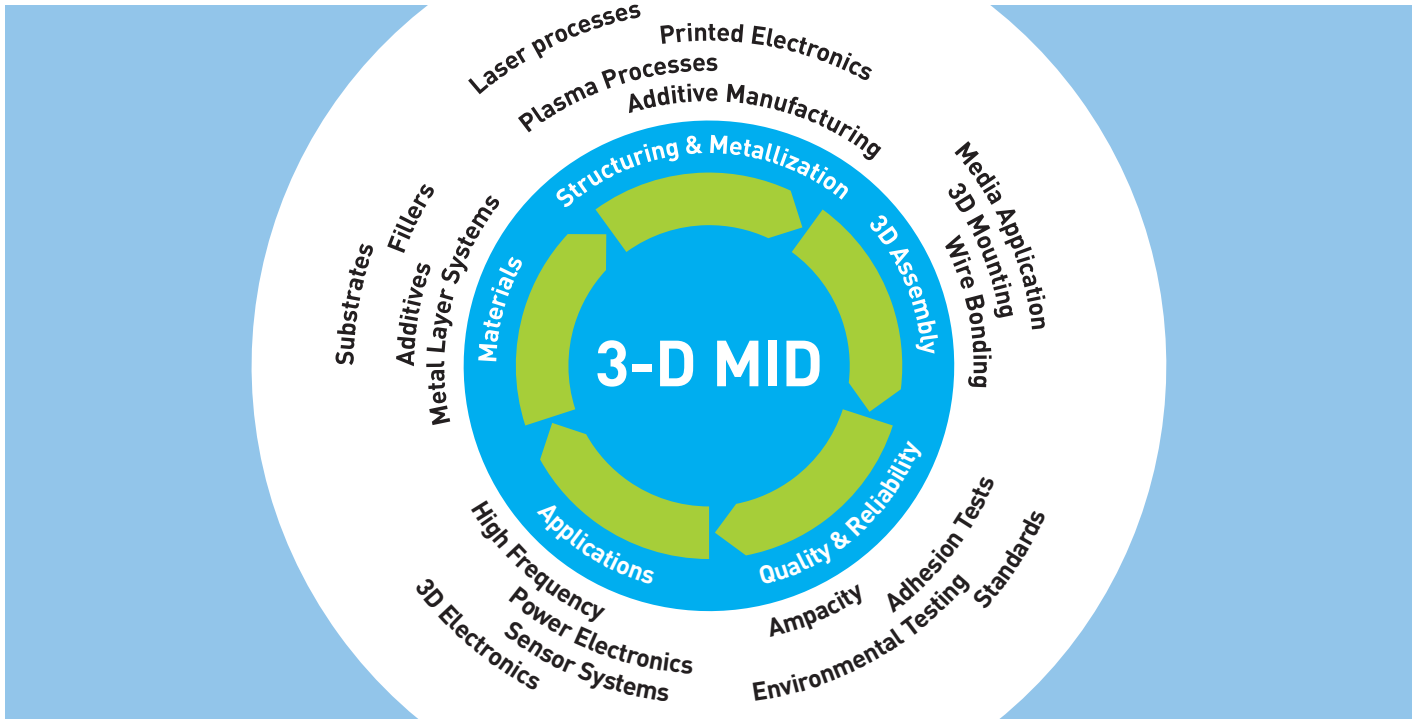
#### Research Association 3-D MID e. V.

Fuerther Str. 246b – GER-90429 Nuremberg

Phone: +49 911 5302-9100

E-Mail: [congress@3dmid.de](mailto:congress@3dmid.de)

[www.3d-mid.de](http://www.3d-mid.de)



## General Information

**Congress Location:** The congress will take place at the Amberg Congress Centrum in Amberg (ACC) in Northern Bavaria. The airport of Nuremberg is within an hour's driving distance by car or train.

**Conference Language:** The conference language is English.

**Research Market:** All our current research projects funded by the German Federal Ministry for Economy (BMWi) and supervised by the Arbeitsgemeinschaft Industrieller Forschungsvereinigungen (AiF) will present their findings in a poster session.

**Exhibition:** The event will be complemented by an accompanying industrial exhibition with booths, table-top-presentations and posters. Further information is available at [www.3dmid.de](http://www.3dmid.de)

**Invited Keynotes:** Distinguished scientists and industrial experts will present groundbreaking discoveries and latest serial applications in MID technology.

The **MID Award 2021** will be granted for outstanding investigation in the field of MID technology by the 3-D MID e.V.

**Best Paper Award:** 3-D MID e.V. honors the best paper and the best presentation with a Best Paper and a Best Presentation Award.

**Technical Tour:** On Wednesday February 10<sup>th</sup>, 2021 a tour through the Industry 4.0 model plant of Siemens AG Amberg is offered.

**Further Information:** For further information visit our website [www.3d-mid.de](http://www.3d-mid.de) or directly contact the 3-D MID e.V. office.

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